Applicant: Renato Conta et al.

Appl. No.: 10/577,431

AMENDMENTS TO THE SPECIFICATION

(1) Please replace current paragraph 0090 of the specification with the following

amended paragraph:

[0090] The distribution channel or main distribution channel 149 extends over the entire length

of the module 131 parallel to the edge 133 and adjacent to it and is in fluid communication with

the delivery channels 138 and with the feeding duct 143 of the support 132. The orifice plate 152

is integrated on the face 141 of the chip 134, delimits the cells 137 and the channels 138 and the

nozzles 139 are made upon it above the ejection cells 137. The sealing means 150 are inserted

between the orifice plate 152 and the support 132 to ensure ink-tightness between the feeding

duct 143 and the cells 137.

(2) Please replace current paragraph 0091 of the specification with the following

amended paragraph:

[0091] In the head 130 of this first embodiment, the distribution channel 149 is produced on the

same face 141 of the chip 134 and ribs 151 are provided that run transversally in the channel 149

for a length "D" between the delivery channels 138 so to form a further distribution channel 149a

orthogonal to the channel 149. The sealing means 150 in turn include a sealing lamina 153,

providing tightness between the orifice plate 152 and the support 132.

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(3) Please replace current paragraph 0098 of the specification with the following

amended paragraph:

[0098] In particular, the ribs 151 extend for a distance "D" of 0.2-0.9 mm in the distribution

channel 149; such a distance is shorter than "Ch" and the ribs are each 15-30 µm wide, while the

gluing area of the layer 152 extends for slightly more than these values towards the nozzles 139.

(4) Please replace current paragraph 0108 of the specification with the following

amended paragraph:

[0108] In accordance with the invention, the manufacturing process of the printhead 130 includes

an etching step 181 (FIG. 11) wherein on the face 141 of each chip block 171 of the wafer 173 a

longitudinal etch 182 is made. The etch 182 is symmetrical with respect to the plane 172, starts at

a distance "C" from the resistors 136 and produces, in the sections 131A and 131B, the

distribution channels 149 and the series of ribs 151 which extend for length "D" in the channels

149 so as to form the further distribution channels 149a.

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